

Serial No. 10/072,743

**Amendments to the Title**

Please replace the title with the following:

**~~RADIUSED LEADFRAME~~ METHOD OF FABRICATING AN INTEGRATED CIRCUIT  
PACKAGE**

**Amendments to the Specification:**

Please replace the first full paragraph on page 2 with the following:

This application is a continuation of application Serial No. 09/004,214, filed January 9, 1998, ~~pending~~, now US Patent No. 6,362,426 issued March 26, 2002.

BI